

CRYSTAL OSCILLATOR (Programmable)

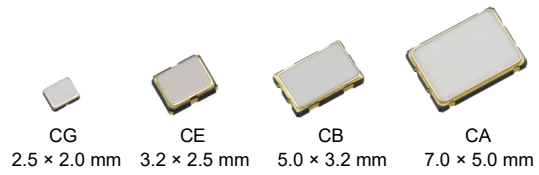
OUTPUT: CMOS

SG-8018 series

- Frequency range : 0.67 MHz to 170 MHz (1 ppm Step)
- Supply voltage : 1.62 V to 3.63 V
- Function : Output enable (OE) or Standby (ST)
- Frequency tolerance : ±50 ppm (-40 °C to +105 °C)
Including frequency aging(+25 °C, 10 years)
- PLL technology to enable short lead time
- Available field oscillator programmer "SG-Writer II"



Product Number
SG-8018CG: X1G005601xxxx00
SG-8018CE: X1G005591xxxx00
SG-8018CB: X1G005581xxxx00
SG-8018CA: X1G005571xxxx00



Specifications (characteristics)

Item	Symbol	Specifications				Conditions/Remarks																																							
Supply voltage	V _{CC}	1.80 V Typ.		2.50 V Typ.	3.30 V Typ.		-																																						
		1.62 V to 1.98 V	1.98 V to 2.20 V	2.20 V to 2.80 V	2.70 V to 3.63 V																																								
Output frequency range	f _o	0.67 MHz to 170 MHz																																											
Storage temperature range	T _{stg}	-40 °C to +125 °C				Storage as single product.																																							
Operating temperature range	T _{use}	-40 °C to +105 °C				-																																							
Frequency tolerance ^{*1}	f _{tol}	J: ±50 × 10 ⁻⁶				T _{use} = -40 °C to +105 °C																																							
Current consumption	I _{CC}	3.2 mA Max.	3.3 mA Max.	3.4 mA Max.	3.5 mA Max.	T _{use} = +105 °C	No load, f _o = 20 MHz																																						
		2.7 mA Typ.		2.9 mA Typ.	3.0 mA Typ.	T _{use} = +25 °C																																							
		5.5 mA Max.	5.8 mA Max.	6.7 mA Max.	8.1 mA Max.	T _{use} = +105 °C	No load, f _o = 170 MHz																																						
		4.7 mA Typ.		5.7 mA Typ.	6.8 mA Typ.	T _{use} = +25 °C																																							
Output disable current	I _{dis}	3.2 mA Max.	3.2 mA Max.	3.3 mA Max.	3.5 mA Max.	OE = GND, f _o = 170 MHz																																							
Standby current	I _{std}	0.9 µA Max.	1.0 µA Max.	1.5 µA Max.	2.5 µA Max.	T _{use} = +105 °C	ST = GND																																						
		0.3 µA Typ.	0.4 µA Typ.	0.5 µA Typ.	1.1 µA Typ.	T _{use} = +25 °C																																							
Symmetry	SYM	45 % to 55 %				50 % V _{CC} Level																																							
Output voltage (DC characteristics)	V _{OH}	90 % V _{CC} Min.				I _{OH} /I _{OL} Conditions [mA]																																							
	V _{OL}	10 % V _{CC} Max.				<table border="1"> <thead> <tr> <th>Rise/Fall time</th> <th>V_{CC}</th> <th>*A</th> <th>*B</th> <th>*C</th> <th>*D</th> </tr> </thead> <tbody> <tr> <td rowspan="2">Default (f_o > 40 MHz), Fast</td> <td>I_{OH}</td> <td>-2.5</td> <td>-3.5</td> <td>-4.0</td> <td>-5.0</td> </tr> <tr> <td>I_{OL}</td> <td>2.5</td> <td>3.5</td> <td>4.0</td> <td>5.0</td> </tr> <tr> <td rowspan="2">Default (f_o ≤ 40 MHz)</td> <td>I_{OH}</td> <td>-1.5</td> <td>-2.0</td> <td>-2.5</td> <td>-3.0</td> </tr> <tr> <td>I_{OL}</td> <td>1.5</td> <td>2.0</td> <td>2.5</td> <td>3.0</td> </tr> <tr> <td rowspan="2">Slow</td> <td>I_{OH}</td> <td>-1.0</td> <td>-1.5</td> <td>-2.0</td> <td>-2.5</td> </tr> <tr> <td>I_{OL}</td> <td>1.0</td> <td>1.5</td> <td>2.0</td> <td>2.5</td> </tr> </tbody> </table>		Rise/Fall time	V _{CC}	*A	*B	*C	*D	Default (f _o > 40 MHz), Fast	I _{OH}	-2.5	-3.5	-4.0	-5.0	I _{OL}	2.5	3.5	4.0	5.0	Default (f _o ≤ 40 MHz)	I _{OH}	-1.5	-2.0	-2.5	-3.0	I _{OL}	1.5	2.0	2.5	3.0	Slow	I _{OH}	-1.0	-1.5	-2.0	-2.5	I _{OL}	1.0	1.5	2.0
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	I _{OL}	1.0	1.5	2.0	2.5																																								
Output load condition	L _{CMOS}	15 pF Max.				-																																							
Input voltage	V _{IH}	70 % V _{CC} Min.				OE or ST																																							
	V _{IL}	30 % V _{CC} Max.																																											
Rise time /Fall time	Default / Fast / Slow	tr/tf	3.0 ns Max.			f _o > 40 MHz																																							
			6.0 ns Max.			f _o ≤ 40 MHz																																							
			3.0 ns Max.			f _o = 0.67 MHz to 170 MHz																																							
			10.0 ns Max.			f _o = 0.67 MHz to 20 MHz																																							
Output disable time (OE)	tstp_oe	1 µs Max.				Measured from the time OE or ST pin crosses 30 % V _{CC}																																							
Output disable time (ST)	tstp_st	1 µs Max.				Measured from the time OE pin crosses 70 % V _{CC}																																							
Output enable time (OE)	tsta_oe	1 µs Max.				Measured from the time OE pin crosses 70 % V _{CC}																																							
Output enable time (ST)	tsta_st	3 ms Max.				Measured from the time ST pin crosses 70 % V _{CC}																																							
Start-up time	t _{str}	3 ms Max.				Measured from the time V _{CC} reaches its rated minimum value, 1.62 V																																							
Frequency aging	f _{age}	This is included in frequency tolerance specification.				+25 °C, 10 years																																							

*1 Frequency tolerance includes initial frequency tolerance, frequency / temperature characteristics, frequency / voltage coefficient, frequency / load coefficient and frequency aging (+25 °C, 10 years).

Pin description

Pin	Name	I/O type	Function	
1	OE	Input	Output enable	High ^{*2} : Specified frequency output from OUT pin Low: Out pin is low (weak pull down), only output driver is disabled.
	ST	Input	Standby	High ^{*2} : Specified frequency output from OUT pin Low: Out pin is low (weak pull down), Device goes to standby mode. Supply current reduces to the least as I _{std} .
2	GND	Power	Ground	
3	OUT	Output	Clock output	
4	V _{CC}	Power	Power supply	

*2 Please do not use the OE/ST terminal in the open state.



Product Name

SG-8018CG 25.000000MHz T J H P A
① ② ③ ④⑤⑥⑦⑧

- ① Model
- ② Package type
- ③ Frequency
- ④ Supply voltage (T: 1.8 V to 3.3 V Typ.)
- ⑤ Frequency tolerance (J: $\pm 50 \times 10^{-6}$)
- ⑥ Operating temperature (H: -40 °C to +105 °C)
- ⑦ Function
- ⑧ Rise/Fall time

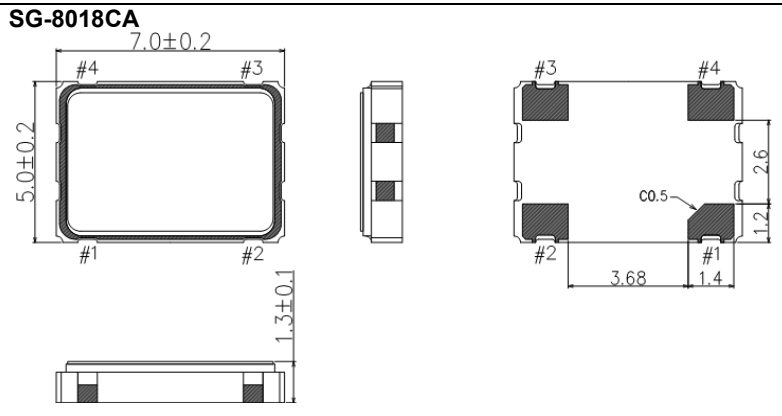
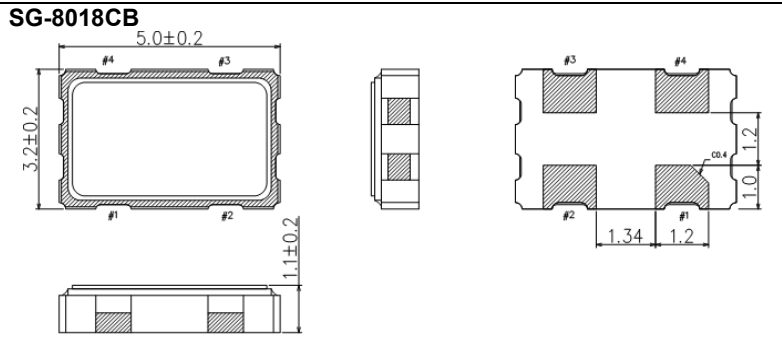
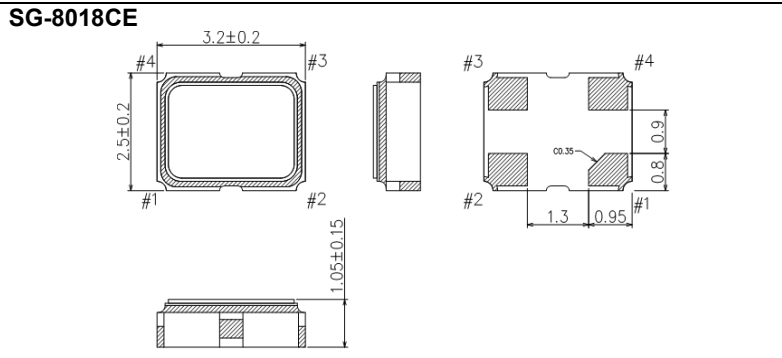
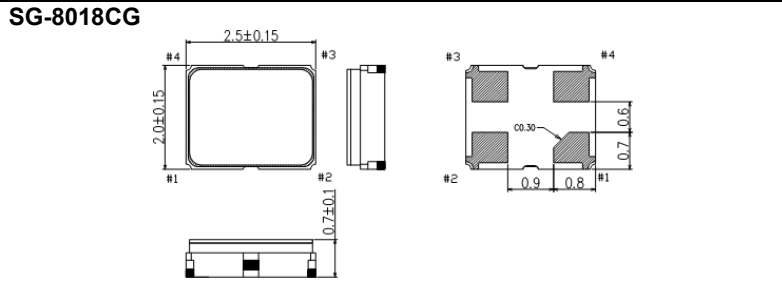
② Package type	
CG	2.5 mm × 2.0 mm
CE	3.2 mm × 2.5 mm
CB	5.0 mm × 3.2 mm
CA	7.0 mm × 5.0 mm

⑦ Function	
P	Output enable
S	Standby

⑧ Rise time/Fall time	
A	Default
B	Fast
C	Slow

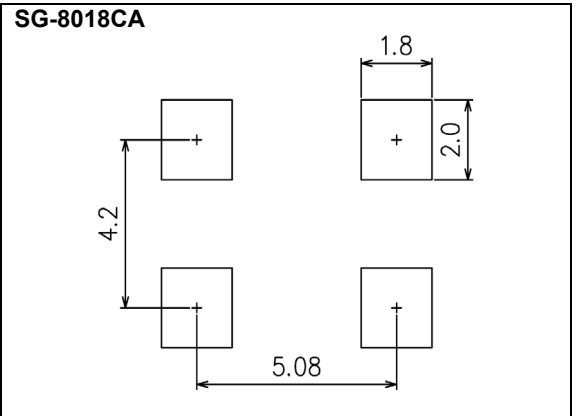
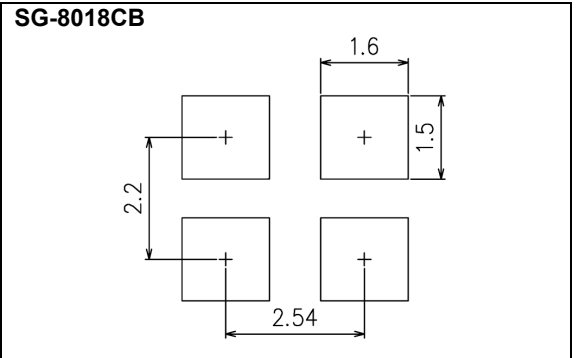
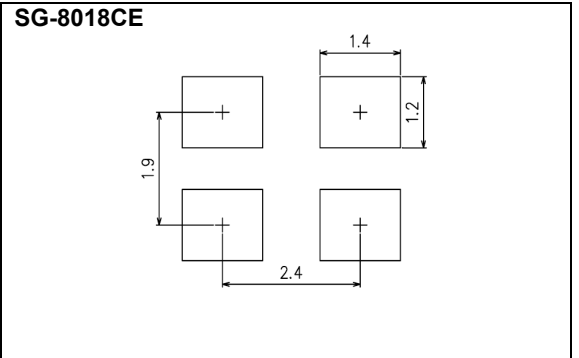
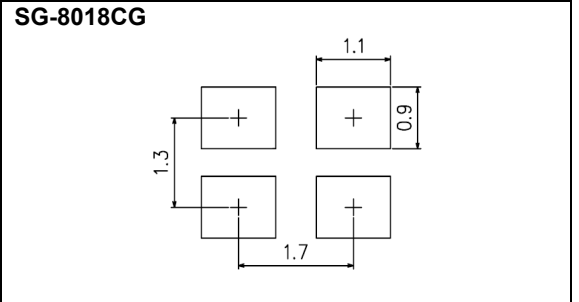
External dimensions

(Unit: mm)



Footprint (Recommended)

(Unit: mm)



Notes:

In order to achieve optimum jitter performance, the 0.1 μF capacitor between V_{CC} and GND should be placed. It is also recommended that the capacitors are placed on the device side of the PCB, as close to the device as possible and connected together with short wiring pattern.

PROMOTION OF ENVIRONMENTAL MANAGEMENT SYSTEM CONFORMING TO INTERNATIONAL STANDARDS

At Seiko Epson, all environmental initiatives operate under the Plan-Do-Check-Action (PDCA) cycle designed to achieve continuous improvements. The environmental management system (EMS) operates under the ISO 14001 environmental management standard.

All of our major manufacturing and non-manufacturing sites, in Japan and overseas, completed the acquisition of ISO 14001 certification.

ISO 14000 is an international standard for environmental management that was established by the International Standards Organization in 1996 against the background of growing concern regarding global warming, destruction of the ozone layer, and global deforestation.

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IATF 16949 is the international standard that added the sector-specific supplemental requirements for automotive industry based on ISO9001.

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	► Pb free.
	► Complies with EU RoHS directive. *About the products without the Pb-free mark. Contains Pb in products exempted by EU RoHS directive. (Contains Pb in sealing glass, high melting temperature type solder or other.)
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